## BUT11F

### **GENERAL DESCRIPTION**

High-voltage, high-speed glass-passivated npn power transistor in a SOT186 envelope with electrically insulated mounting base, intended for use in converters, inverters, switching regulators, motor control systems, etc.

### QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V <sub>CESM</sub> V <sub>CEO</sub>	Collector-emitter voltage peak value Collector-emitter voltage (open base)	$V_{BE} = 0 V$	-	850 400	V V
l <sub>c</sub>	Collector current (DC) Collector current peak value		-	5	Â
P <sub>tot</sub> V <sub>CEsat</sub>	Total power dissipation Collector-emitter saturation voltage	$T_{hs} \le 25 \ ^{\circ}C$	-	20 1.5	Ŵ V
I <sub>Csat</sub>	Collector saturation current Fall time		-	3 800	A ns

### [INCLUDE]

#### LIMITING VALUES

Limiting values in accordance with the Absolute Maximum Rating System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CESM</sub>	Collector-emitter voltage peak value	$V_{BF} = 0 V$	-	850	V
V <sub>CEO</sub>	Collector-emitter voltage (open base)		-	450	V
I <sub>c</sub>	Collector current (DC)		-	5	A
I <sub>CM</sub>	Collector current peak value		-	10	A
IB	Base current (DC)		-	2	A
I <sub>BM</sub>	Base current peak value		-	4	A
P <sub>tot</sub>	Total power dissipation	T <sub>hs</sub> ≤ 25 °C	-	20	W
T <sub>stg</sub>	Storage temperature		-65	150	°C
T <sub>j</sub>	Junction temperature		-	150	°C

### THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
R <sub>th j-hs</sub>	Junction to heatsink	with heatsink compound	-	3.95	K/W
R <sub>th j-a</sub>	Junction to ambient	in free air	55	-	K/W

#### **ISOLATION LIMITING VALUE & CHARACTERISTIC**

 $T_{hs} = 25$  °C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>isol</sub>	Repetitive peak voltage from all three terminals to external heatsink	$R.H. \leq 65\%$ ; clean and dustfree	-		1500	V
C <sub>isol</sub>	Capacitance from T2 to external heatsink	f = 1 MHz	-	12	-	pF

# BUT11F

### STATIC CHARACTERISTICS

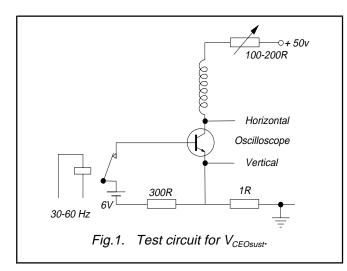
 $T_{hs} = 25$  °C unless otherwise specified

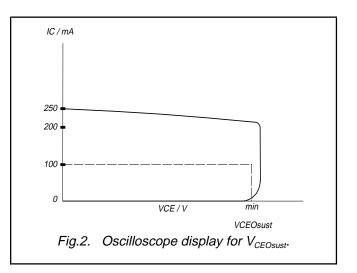
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CES</sub>	Collector cut-off current <sup>1</sup>		-	-	1.0	mA
I <sub>CES</sub>		$V_{BE} = 0 V; V_{CE} = V_{CESMmax};$ T <sub>i</sub> = 125 °C	-	-	2.0	mA
I <sub>EBO</sub>	Emitter cut-off current	$V_{rp} = 9 V; I_{c} = 0 A$	-	-	10	mA
V <sub>CEOsust</sub>	Collector-emitter sustaining voltage	$I_B = 0 \text{ A}; I_C = 100 \text{ mA};$ L = 25 mH	450	-	-	V
V <sub>CEsat</sub>	Collector-emitter saturation voltages	$I_{c} = 3.0 \text{ A}; I_{B} = 0.6 \text{ A}$	-	-	1.5	V
V <sub>BEsat</sub>	Base-emitter saturation voltage	$I_{c} = 3.0 \text{ A}; I_{B} = 0.6 \text{ A}$	-	-	1.3	V
h <sub>FE</sub>	DC current gain	$I_{c} = 5 \text{ mA}; V_{ce} = 5 \text{ V}$	10	18	35	
h <sub>FE</sub>		$I_{c} = 500 \text{ mA}; V_{ce} = 5 \text{ V}$	10	20	35	

#### **DYNAMIC CHARACTERISTICS**

 $T_{hs}$  = 25 °C unless otherwise specified

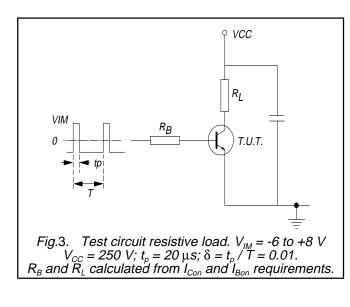
SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
t <sub>on</sub> t <sub>s</sub> t <sub>f</sub>	Switching times (resistive load) Turn-on time Turn-off storage time Turn-off fall time	$I_{Con} = 2.5 \text{ A}; I_{Bon} = -I_{Boff} = 0.5 \text{ A}$	- - -	1 4 0.8	μs μs μs
t <sub>s</sub> t <sub>f</sub>	Switching times (inductive load) Turn-off storage time Turn-off fall time		1.1 80	1.4 150	μs ns
t <sub>s</sub> t <sub>f</sub>	Switching times (inductive load) Turn-off storage time Turn-off fall time	$      I_{Con} = 2.5 \text{ A}; I_{Bon} = 0.5 \text{ A}; L_{B} = 1  \mu\text{H}; \\ -V_{BB} = 5 \text{ V}; T_{j} = 100 ^{\circ}\text{C} $	1.2 140	1.5 300	μs ns

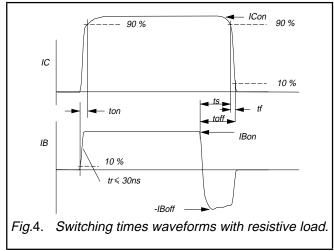


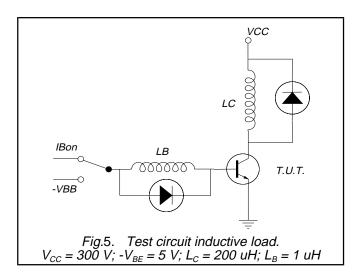


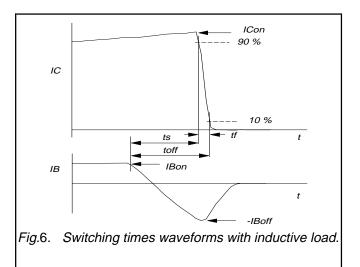
<sup>1</sup> Measured with half sine-wave voltage (curve tracer).

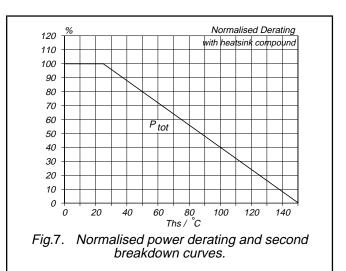
## BUT11F

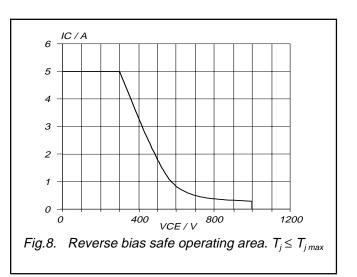




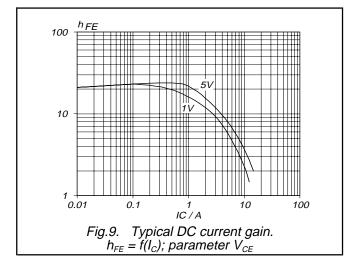


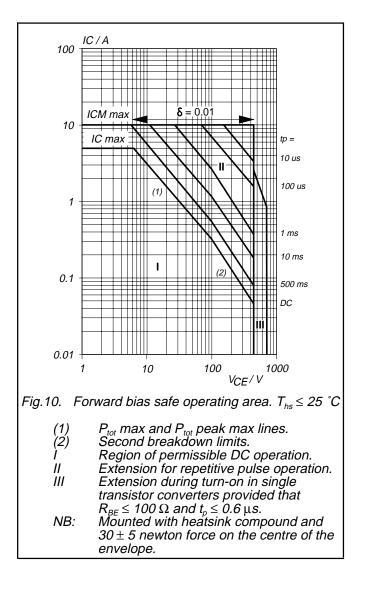




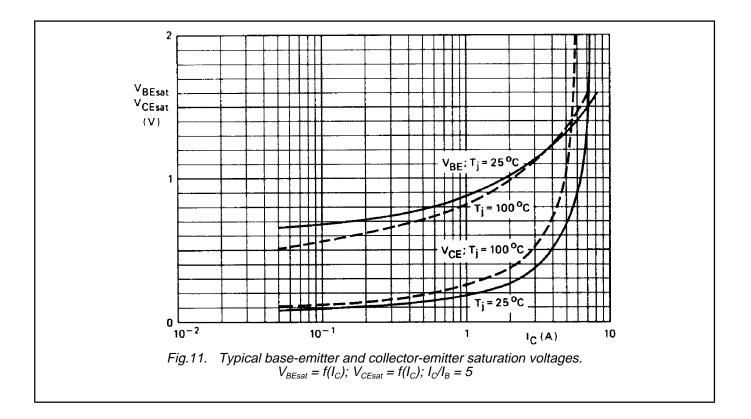


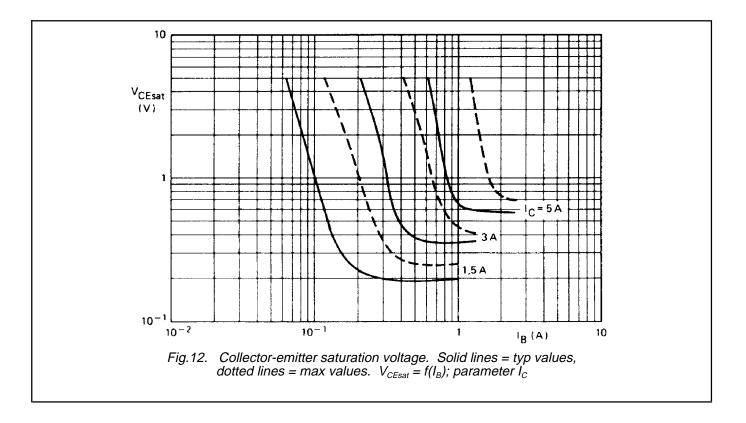
## BUT11F





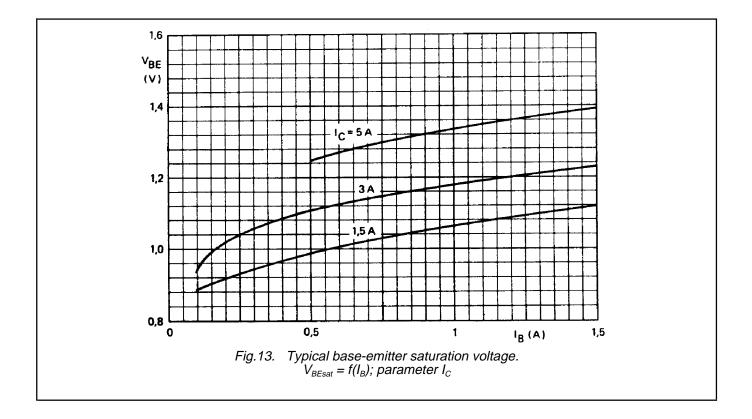
## BUT11F

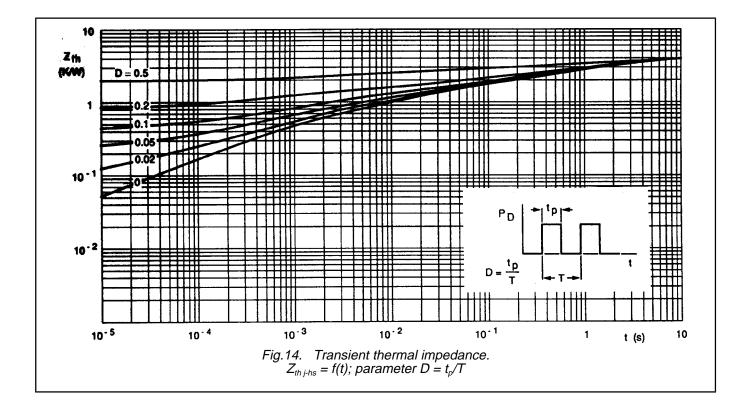




BUT11F

## Silicon Diffused Power Transistor

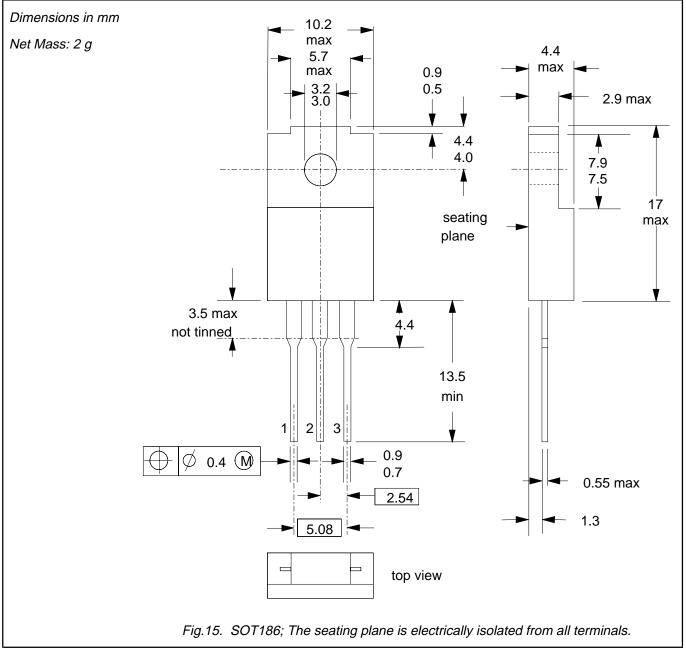




### Product specification

### BUT11F

#### **MECHANICAL DATA**



#### Notes

- Observe the general handling precautions for electrostatic-discharge sensitive devices (ESDs) to prevent damage to MOS gate oxide.
  Refer to mounting instructions for F-pack envelopes.
  Epoxy meets UL94 V0 at 1/8".

BUT11F

#### DEFINITIONS

Data sheet status				
Objective specification	ective specification This data sheet contains target or goal specifications for product development.			
Preliminary specification	eliminary specification This data sheet contains preliminary data; supplementary data may be published later.			
Product specification	This data sheet contains final product specifications.			
Limiting values				
or more of the limiting val operation of the device at	Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.			
Application information				
Where application information is given, it is advisory and does not form part of the specification.				
© Philips Electronics N.V. 1997				
All rights are reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner.				

The information presented in this document does not form part of any quotation or contract, it is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent or other industrial or intellectual property rights.

#### LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices or systems where malfunction of these products can be reasonably expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.